

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6	((bond with pad) with nitrogen) and copper	USPAT; EPO; JPO	OR	OFF	2005/06/24 13:40
L2	127	pad with nitrogen and copper and bond	USPAT; EPO; JPO	OR	OFF	2005/06/24 13:41
L4	1	("6180505").PN.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/06/24 13:47
L5	11	("4661416" "4814049" "5071518" "5098860" "5106461" "5213638" "5308796" "5320689" "5385661" "5656858" "6020640").PN.	US-PGPUB; USPAT; USOCR	AND	OFF	2005/06/24 13:48
L6	6	("5468984" "5656858" "5665991" "5705857" "5739579" "5793112").PN.	US-PGPUB; USPAT; USOCR	AND	OFF	2005/06/24 13:49
L7	11	("4661416" "4814049" "5071518" "5098860" "5106461" "5213638" "5308796" "5320689" "5385661" "5656858" "6020640").PN.	US-PGPUB; USPAT; USOCR	AND	OFF	2005/06/24 13:54
L8	1	("6613671").PN.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/06/24 13:56
L9	1	("5892179").PN.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/06/24 14:05
L10	1	("6423625").PN.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/06/24 14:05
L11	2	("5773359" "5937320").PN.	US-PGPUB; USPAT; USOCR	AND	OFF	2005/06/24 14:42
L12	2472	(257/762-764).CCLS.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/06/24 14:43
L13	1200	257/762-764.ccls. and copper	US-PGPUB; USPAT; EPO; JPO	AND	OFF	2005/06/24 14:43
L14	2	257/762-764.ccls. and copper and apd	US-PGPUB; USPAT; EPO; JPO	AND	OFF	2005/06/24 14:43
L15	327	257/762-764.ccls. and copper and pad	US-PGPUB; USPAT; EPO; JPO	AND	OFF	2005/06/24 14:43

L16	467	257/770,774.ccls. and copper and pad	US-PGPUB; USPAT; EPO; JPO	AND	OFF	2005/06/24 14:44
L17	2583	(257/770,774).CCLS.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/06/24 14:44
S1	1	"20040056361".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2004/08/30 10:39
S2	1	("6300688").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/08/30 11:04
S3	1	("3755089").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/08/30 11:05
S4	1	("4341846").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/08/30 11:05
S5	1	("4910169").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/08/30 11:12
S6	1	("4987750").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/08/30 11:13
S7	1	("4995552").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/08/30 11:13
S8	1	("5021296").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/08/30 11:13
S9	1	("5231306").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/08/30 11:20
S10	1	("5472563").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/08/30 11:21
S11	1	("5518760").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/08/30 11:23
S12	1	("5703408").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/08/30 11:24
S13	1	("5776617").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/08/30 11:25
S14	1	("5804908").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/08/30 11:25

S15	1	("5939788").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/08/30 11:33
S16	1	("6165885").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/08/30 11:34
S17	1	("6218302").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/08/30 12:50
S18	14	("5063169" "5130274" "5169680" "5243222" "5391517" "5622608" "5674787" "5677244" "5747360" "5821168" "5824599" "5891513" "5933758" "5939788").PN.	USPAT	OR	OFF	2004/08/30 11:39
S19	2	("4021277" "4415427").PN.	USPAT	OR	OFF	2004/08/30 12:16
S20	6	"5622608".URPN.	USPAT	OR	OFF	2004/08/30 12:16
S21	7	("5622608" "6057223" "6066892" "6111301" "6180503" "6249055" "6295721" "2001/0042897").PN.	USPAT	OR	OFF	2004/08/30 12:17
S22	1	("6268291").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/08/30 13:07
S23	3216	(seed adj layer) and copper	USPAT; EPO; JPO	OR	OFF	2004/08/30 13:07
S24	838	(seed adj layer) and copper and pad	USPAT; EPO; JPO	OR	OFF	2004/08/30 13:32
S25	727	(seed adj layer) and copper and pad and thickness	USPAT; EPO; JPO	OR	OFF	2004/08/30 14:13
S26	1	("6218732").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/08/30 13:40
S27	3	("4827326" "5365112" "6013571").PN.	USPAT	OR	OFF	2004/08/30 13:50
S28	4	("6083835" "6143155" "6315883" "6582579").PN.	USPAT	OR	OFF	2004/08/30 14:10
S29	388	((seed adj layer) same thickness) and copper and pad and thickness	USPAT; EPO; JPO	OR	OFF	2004/08/30 15:35
S30	5	("6156149" "6228760" "6458689" "6620745" "6638853").PN.	USPAT	OR	OFF	2004/08/30 14:16
S31	10	("5654581" "6117747" "6144051" "6159793" "6174804" "6174812" "6329234" "6335557" "6346454" "6433379").PN.	USPAT	OR	OFF	2004/08/30 14:19

S32	14	("5063169" "5130274" "5169680" "5243222" "5391517" "5622608" "5674787" "5677244" "5747360" "5821168" "5824599" "5891513" "5933758" "5939788").PN.	USPAT	OR	OFF	2004/08/30 14:38
S33	502	257/762,763,764,770,774.ccls. and pad and copper	USPAT; EPO; JPO	OR	OFF	2004/08/30 15:37
S34	83	257/762,763,764,770,774.ccls. and pad and copper and nitrogen	USPAT; EPO; JPO	OR	OFF	2004/08/30 15:55
S35	0	"20040056361".pn.	USPAT; EPO; JPO	OR	OFF	2004/07/17 12:18
S36	1	"20040056361".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/06/24 13:47
S37	1	("6642623").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/07/17 13:08
S38	1159	((bond or bonding) adj pad) and copper and titanium	USPAT; EPO; JPO	OR	OFF	2005/06/23 15:49
S39	5	((bond or bonding) adj pad) and copper and (titanium.ti.)	USPAT; EPO; JPO	OR	OFF	2005/06/23 15:48
S40	3	((bond or bonding) adj pad) and ((dope or implant) with copper)	USPAT; EPO; JPO	OR	OFF	2004/07/17 13:22
S41	13	((bond or bonding) with pad) and ((dope or implant) with titanium)	USPAT; EPO; JPO	OR	OFF	2004/07/17 13:25
S42	431	((bond adj pad) or (bonding adj pad)).ti.	USPAT; EPO; JPO	OR	OFF	2004/07/17 13:27
S43	100	((bond adj pad) or (bonding adj pad)).ti. and (ti or titanium)	USPAT; EPO; JPO	OR	OFF	2004/07/17 13:33
S44	1	"2000183104".pn.	USPAT; EPO; JPO	OR	OFF	2004/07/18 10:24
S45	6	("3585461" "4093110" "5036383" "5455195" "5734200" "5976964").PN.	USPAT	OR	OFF	2004/07/17 13:38
S46	9	("4136434" "4276557" "4329706" "4398335" "4636832" "4823181" "4872050" "4926222" "4929988").PN.	USPAT	OR	OFF	2004/07/17 13:42
S47	29	"5036383".URPN.	USPAT	OR	OFF	2004/07/17 13:42

S48	16	("4278989" "4364166" "4398335" "4600658" "4755480" "4800177" "4916397" "4948747" "4975875" "4984056" "5036383" "5057447" "5102827" "5262846" "5373192" "5432129").PN.	USPAT	OR	OFF	2004/07/17 13:44
S49	7	("3879746" "4811076" "4811078" "4855801" "4890141" "4903110" "4914500").PN.	USPAT	OR	OFF	2004/07/17 13:47
S50	16	"4984056".URPN.	USPAT	OR	OFF	2004/07/17 13:48
S51	16	("4278989" "4364166" "4398335" "4600658" "4755480" "4800177" "4916397" "4948747" "4975875" "4984056" "5036383" "5057447" "5102827" "5262846" "5373192" "5432129").PN.	USPAT	OR	OFF	2004/07/17 13:49
S52	13	("4278989" "4364166" "4398335" "4600658" "4800177" "4916397" "4948747" "4984056" "5036383" "5057447" "5102827" "5373192" "5432129").PN.	USPAT	OR	OFF	2004/07/17 13:49
S53	3	("3609470" "4566026" "4636832").PN.	USPAT	OR	OFF	2004/07/17 13:51
S54	7	("3383568" "3409809" "3419765" "3429029" "3436616" "3442012" "3465209").PN.	USPAT	OR	OFF	2004/07/17 13:55
S55	0	09/624002	USPAT; EPO; JPO	OR	OFF	2004/07/18 10:24
S56	1	("6314011").PN.	USPAT; USOCR; EPO; JPO	OR	OFF	2004/07/18 12:29
S57	13202	anisotropically	USPAT; EPO; JPO	OR	OFF	2004/07/18 12:29
S58	4390	anisotropically adj etching	USPAT; EPO; JPO	OR	OFF	2004/07/18 12:30
S59	3923	(anisotropically adj etching) and semiconductor	USPAT; EPO; JPO	OR	OFF	2004/07/18 12:31
S60	471	(method with (anisotropic adj etch)) and semiconductor	USPAT; EPO; JPO	OR	OFF	2004/07/18 12:31
S61	3849	(257/762,763,764,770,774).CCLS.	USPAT; EPO; JPO	OR	OFF	2005/03/17 14:12

S62	4508	(257/762,763,764,770,774).CCLS.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/03/17 14:12
S63	938	257/762,763,764,770,774.ccls. and pad	USPAT; EPO; JPO	OR	OFF	2005/03/17 14:13
S64	546	257/762,763,764,770,774.ccls. and pad and copper	USPAT; EPO; JPO	OR	OFF	2005/03/17 16:56
S65	2468	anisotropically with method	USPAT; EPO; JPO	OR	OFF	2005/03/17 16:57
S66	0	anisotropic with method with various	USPAT; EPO; JPO	OR	OFF	2005/03/17 16:57
S67	178	anisotropic with method with different	USPAT; EPO; JPO	OR	OFF	2005/03/17 16:58
S68	22	anisotropic with method with different with etch	USPAT; EPO; JPO	OR	OFF	2005/03/17 17:00
S69	23	anisotropic with method with type with etch	USPAT; EPO; JPO	OR	OFF	2005/03/17 17:00
S70	1	("4666569").PN.	USPAT; EPO; JPO	OR	OFF	2005/03/18 21:31
S71	1	"11317546".pn.	USPAT; EPO; JPO	OR	OFF	2005/03/18 21:45
S72	0	"20040130002".pn.	USPAT; EPO; JPO	OR	OFF	2005/03/18 21:46
S73	1	"20040130002".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/03/18 21:46
S74	3063	algan and gan	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/03/18 21:46
S75	2957	algan and gan and semiconductor	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/03/18 21:46
S76	2540	algan and gan and semiconductor and light	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/03/18 21:47
S77	1782	algan and gan and semiconductor and light and gallium	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/03/18 21:47
S78	816	algan and gan and semiconductor and light and gallium	USPAT; EPO; JPO	OR	OFF	2005/03/18 21:50
S79	14	algan adj cap and gan and semiconductor and light and gallium	USPAT; EPO; JPO	OR	OFF	2005/03/18 21:50
S80	1	("5814861").PN.	USPAT; EPO; JPO	OR	OFF	2005/03/19 12:37
S81	0	"20020190284" .pn.	USPAT; EPO; JPO	OR	OFF	2005/03/19 12:37

S82	1	"20020190284" .pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/03/19 12:37
S83	1	("6642623").PN.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/06/21 13:35
S84	1	("6373137").PN.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/06/21 13:35
S85	6	((bond or bonding) with pad) and copper and (titanium.ti.)	USPAT; EPO; JPO	OR	OFF	2005/06/23 15:48
S86	237	((bond or bonding) with pad) and copper and (titanium with pad)	USPAT; EPO; JPO	OR	OFF	2005/06/23 15:49
S87	386	((bond or bonding) with pad) and copper and (titanium with pad)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/06/23 16:48
S88	62	((copper adj titanium) or (titanium adj copper)) with pad	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/06/23 16:51
S89	11	((((copper adj titanium) or (titanium adj copper)) with alloy) with pad	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/06/23 17:24
S90	1	("5892179").PN.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/06/23 17:24